



DMMT3906

MATCHED PNP SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

Epitaxial Planar Die Construction Intrinsically Matched PNP Pair (Note 1)

Small Surface Mount Package

2% hFE Matched Tolerance

Lead Free/RoHS Compliant (Note 3)

"Green" Device (Note 5 and 6)

Mechanical Data

Case: SOT-26

Case Material: Molded Plastic, "Green" Molding Compound, Note 6. UL Flammability Classification

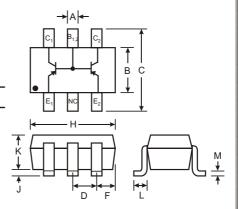
Rating 94V-0

Terminal Connections: See Diagram

Terminals: Solderable per MIL-STD-202, Method 208 Lead Free Plating (Matte Tin Finish annealed over

Copper leadframe).

Marking Information - See page 2 Ordering Information: See Below Weight: 0.015 grams (approximate)



SOT-26								
Dim	Min	Max	Тур					
Α	0.35	0.50	0.38					
В	1.50	1.70	1.60					
С	2.70	3.00	2.80					
D			0.95					
F			0.55					
Н	2.90	3.10	3.00					
J	0.013	0.10	0.05					
K	1.00	1.30	1.10					
L	0.35	0.55	0.40					
M	0.10	0.20	0.15					
All Dimensions in mm								

$@ T_A = 25 C$ unless otherwise specified **Maximum Ratings**

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	V _{CBO}	-40	V	
Collector-Emitter Voltage	V _{CEO}	-40	V	
Emitter-Base Voltage	V _{EBO}	-5.0	V	
Collector Current - Continuous	Ic	-200	mA	
Power Dissipation (Note 2)	Pd	225	mW	
Thermal Resistance, Junction to Ambient (Note 2)	R JA	556	C/W	
Operating and Storage and Temperature Range	T _j , T _{STG}	-55 to +150	С	

Ordering Information (Note 4 & 6)

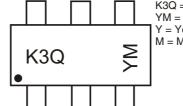
Device	Packaging	Shipping		
DMMT3906-7-F	SOT-26	3000/Tape & Reel		

Notes: Built with adjacent die from a single wafer.

- Device mounted on FR5 PCB: 1.0 x 0.75 x 0.62 in.; pad layout as shown on suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.
- 3. No purposefully added lead.
- For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



Marking Information



K3Q = Product Type Marking Code YM = Date Code Marking Y = Year ex: T = 2006 M = Month ex: 9 = September

Date Code Key

Year	2004	20	05	2006	2007	- 2	2008	2009	20	10 2	2011	2012
Code	R		3	Т	U		V	W	X		Υ	Z
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

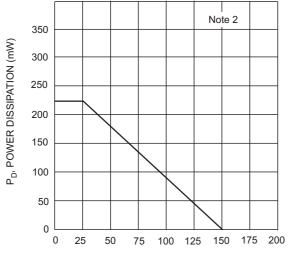
Electrical Characteristics @ T_A = 25 C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition			
OFF CHARACTERISTICS (Note 7)								
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-40		V	I _C = -10 A, I _E = 0			
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	-40		V	I _C = -1.0mA, I _B = 0			
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	-5.0		V	I _E = -10 A, I _C = 0			
Collector Cutoff Current	I _{CEX}		-50	nA	V _{CE} = -30V, V _{EB(OFF)} = -3.0V			
Base Cutoff Current	I _{BL}		-50	nA	V _{CE} = -30V, V _{EB(OFF)} = -3.0V			
ON CHARACTERISTICS (Note 7)								
DC Current Gain (Note 8)	h _{FE}	60 80 100 60 30	300		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$			
Collector-Emitter Saturation Voltage	V _{CE(SAT)}		-0.25 -0.40	V	I _C = -10mA, I _B = -1.0mA I _C = -50mA, I _B = -5.0mA			
Base-Emitter Saturation Voltage	V _{BE(SAT)}	-0.65	-0.85 -0.95	V	I _C = -10mA, I _B = -1.0mA I _C = -50mA, I _B = -5.0mA			
SMALL SIGNAL CHARACTERISTICS	, ,		'					
Output Capacitance	C _{obo}		4.5	pF	$V_{CB} = -5.0V$, $f = 1.0MHz$, $I_E = 0$			
Input Capacitance	Cibo		10	pF	$V_{EB} = -0.5V$, $f = 1.0MHz$, $I_C = 0$			
Input Impedance	h _{ie}	2.0	12	k				
Voltage Feedback Ratio	h _{re}	0.1	10	x 10 ⁻⁴	V _{CE} = 10V, I _C = 1.0mA,			
Small Signal Current Gain	h _{fe}	100	400		f = 1.0kHz			
Output Admittance	h _{oe}	3.0	60	S				
Current Gain-Bandwidth Product	f⊤	250		MHz	$V_{CE} = -20V, I_{C} = -10mA, f = 100MHz$			
Noise Figure	NF		4.0	dB	V _{CE} = -5.0V, I _C = -100 A, R _S = 1.0k f = 1.0kHz			
SWITCHING CHARACTERISTICS								
Delay Time	t _d		35	ns	V _{CC} = -3.0V, I _C = -10mA,			
Rise Time	t _r		35	ns	$V_{BE(off)} = 0.5V, I_{B1} = -1.0mA$			
Storage Time	t _s		225	ns	V _{CC} = -3.0V, I _C = -10mA,			
Fall Time	t _f		75	ns	$I_{B1} = I_{B2} = -1.0 \text{mA}$			

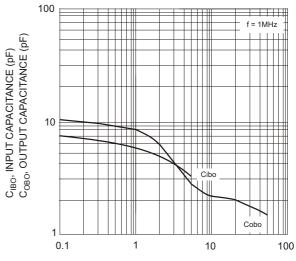
Notes:

- 7. Short duration pulse test used to minimize self-heating effect.
- 8. The DC current gain, hFE, is matched at IC = -10mA and VCE = -1.0V with typical matched tolerances of 1% and maximum of 2%.





T_A, AMBIENT TEMPERATURE (°C) Fig. 1, Max Power Dissipation vs Ambient Temperature, Total Device



 V_{CB} , COLLECTOR-BASE VOLTAGE (V) Fig. 2, Input and Output Capacitance vs.
Collector-Base Voltage

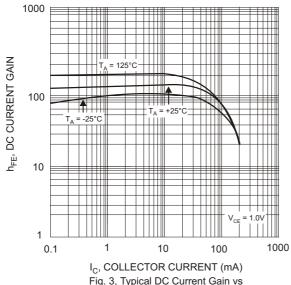
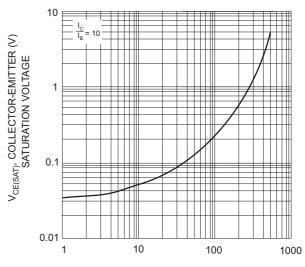
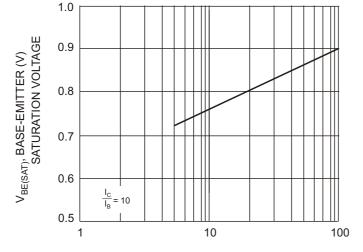


Fig. 3, Typical DC Current Gain vs Collector Current



 $I_{\rm C}$, COLLECTOR CURRENT (mA) Fig. 4, Typical Collector-Emitter Saturation Voltage vs. Collector Current



 I_C , COLLECTOR CURRENT (mA) Fig. 5, Typical Base-Emitter Saturation Voltage vs. Collector Current



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